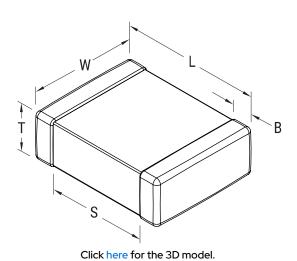




SMD Comm X8G HT150C, Ceramic, 0.01 uF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information			
Series	SMD Comm X8G HT150C		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	30 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

T	0.78mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	
Packaging Specifications		

10000

Packaging

Packaging Quantity

Specifications		
Capacitance	0.01 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	20%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Aging Rate	0% Loss/Dec
Insulation Resistance	100 GOhms

T&R, 330mm, Plastic Tape

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/03/2025 © 2006 - 2025 YAGEO